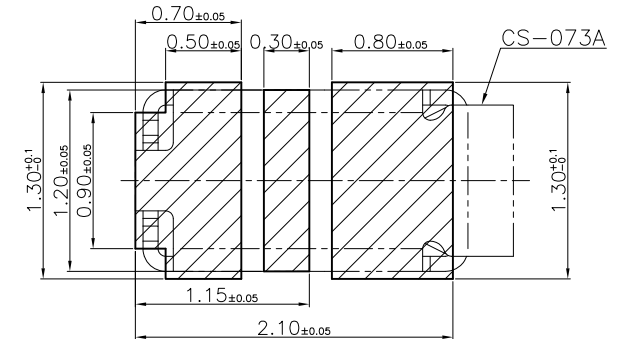
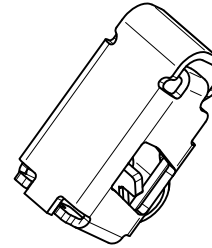
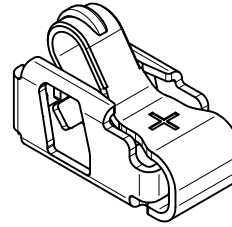
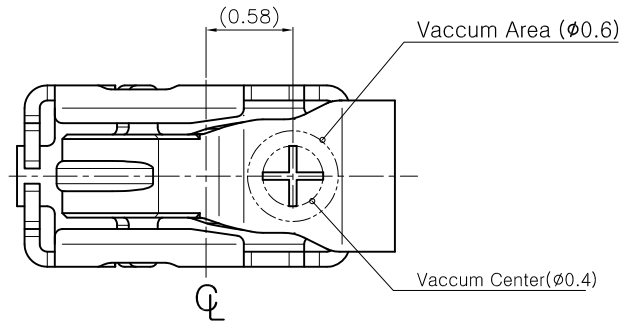
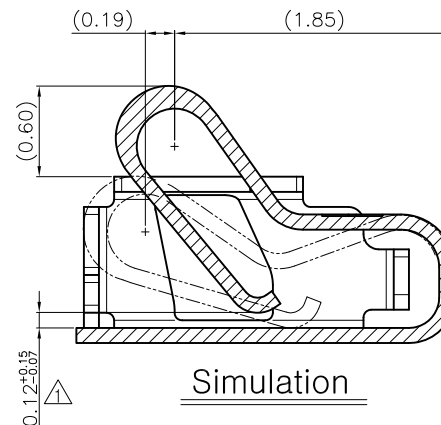
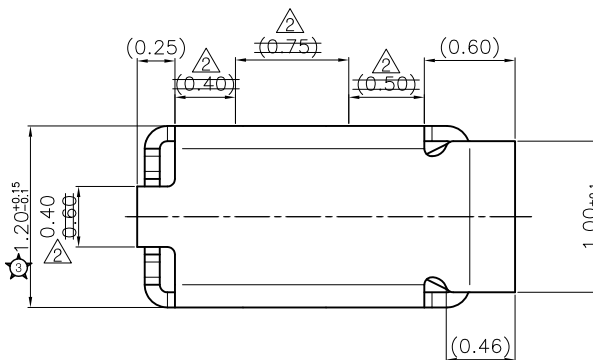
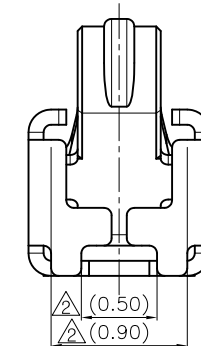
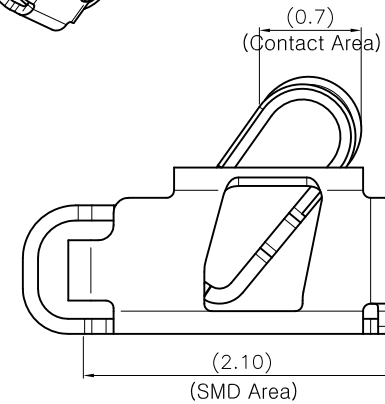
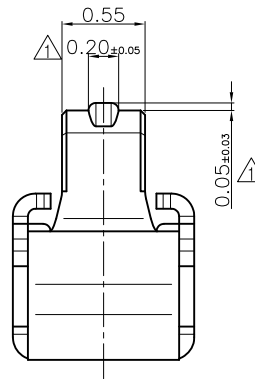
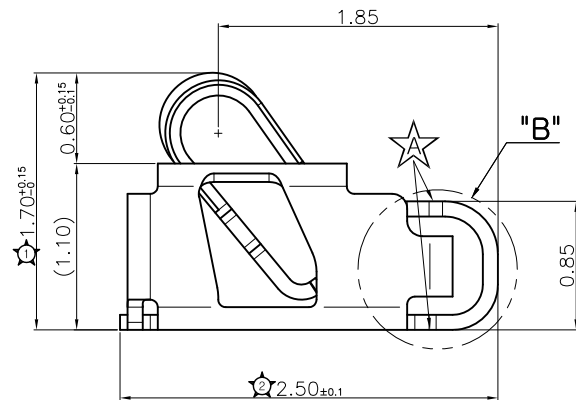


Rev No.	Description	Date	Name	Reviewed	Approved	Remark
① X 3	고객사 요청으로 인한 Spec' 추가	2015.05.07	M.G.Son	Y.J.Park	S.K.Hong	-
② X 6	고객사 요청으로 인한 Wall 무너짐 개선	2015.06.01	M.G.Son	Y.J.Park	S.K.Hong	-



RECOMMENDED PCB LAYOUT(Top View)
(Metal Mask Thick:0.1)



*NOTE

1. PLATING
 - Contact Area : Au 0.05 μ m Min. over Pd-Ni 0.2 μ m Min. over Ni 1.5~4.0 μ m
 - SMD Area : Au 0.05 μ m Min. over Ni 1.5~4.0 μ m
 - Other Area : Ni 1.5~3.5 μ m
2. ☆: C.T.Q
3. ☆: 평탄도 0.05 Max.
4. Contact 가동거리 : 0.6mm
권장 Contact 높이 : 가동거리의 60~90% 범위 내
(0.36~0.54mm) => (1.16~1.34mm)
5. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.



1	Contact	Ti-Cu Alloy				Note. 1		t0.1		
No	Part name	Material				Finish		Remarks		
General Tolerance		Scale	N/S	Units	mm			TITLE	CS-073A	
Dimension	mm (°)	Date 2015. 04. 07				ANTENNA CONTACT				
X	± 0.2	Drawn	Design	Checked	Reviewed	Approved			Customer Drawing	
X.X	± 0.15									
X.XX	± 0.1									
X.XXX	± 0.05									
ANGLE	± 2°	M.G. Son		J.K. Park	Y.J. Park	S.K. Hong	SW No.	RI-CS-073A-A1.DWG	Rev. 2	
 협진커넥터(주) HYUPJIN CONNECTOR Co.,Ltd.						DWG No.		CS-073A-A1		

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